



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Ligang Zhang

Title: SURFACE INDUCTOR

Application No.: 09/997,378

Filed: November 30, 2001

Examiner: Tuyen T. Nguyen

Group Art Unit: 2832

Atty. Docket No.: 026-0024

Confirmation No.: 3513

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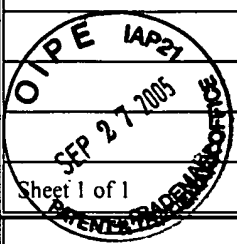
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Respectfully submitted,



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		Application No.: 09/997,378	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		First Named Inventor: Ligang Zhang	
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		Examiner Name: Tuyen T. Nguyen	
		Date Submitted: September 23, 2005	
			
NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No. <sup>1</sup>	Include name of author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
	AA	FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100.	
	AB	KIM, Sung-Jin, et al., "Realization of High-Q Inductors Using Wirebonding Technology," School of Electronics Engineering, Ajou University, AP-ASIG Proceedings, August 1999, 4 pages.	
	AC	LONG, John R. and Miles A. Copeland, "The Modeling, Characterization, and Design of Monolithic Inductors for Silicon RF IC's," IEEE Journal of Solid-State Circuits, Vol. 32, No. 3, March 1997, pp. 357-369.	
	AD	SOH, H. T., et al., "Through-Wafer Vias (TWV) and their Applications in 3 Dimensional Structures," Proceedings of 1998 International Conference on Solid State Devices and Materials, September 1998, 12 pages.	
	AE	TANG, Chih-Chun, et al., "Miniature 3-D Inductors in Standard CMOS Process," IEEE Journal of Solid-State Circuits, Vol. 37, No. 4, April 2002, pp. 471-480.	
	AF	TRELEAVEN, Dave and Dick James, "Integrated Circuit Passive Components," Whitepapers, Chipworks, <a href="http://www.chipworks.com/resources/resources_whitepapers.asp">www.chipworks.com/resources/resources_whitepapers.asp</a> , 4 pages.	
	AG	TSUI, Hau-Yiu and Jack Lau, 2003 IEEE MTT-S Digest, pp. 225-228.	
	AH	WU, Joyce H., et al., "A Through-Wafer Interconnect in Silicon for RFICs," IEEE Transactions on Electron Devices, Vol. 51, No. 11, November 2004, pp. 1765-1771.	
	AI	ZANNOTH, Markus, et al., "A Fully Integrated VCO at 2 GHz," IEEE Journal of Solid-State Circuits, Vol. 33, No. 12, December 1998, pp. 1987-1991.	
	AJ	ZOU, Jun, et al., "Development of Vertical Planar Coil Inductors Using Plastic Deformation Magnetic Assembly (PDMA), 2001 IEEE International Microwave Symposium, May 2001, 4 pages.	
Examiner Signature		Date Considered	

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